

SMART-B1640III

Chip of IC
IC晶片

Material	工件材質	Silicon Carbide (碳化矽)
Hardness	工件硬度	HRC20
Machining Size	加工尺寸	305x800mm(WxH)
Machining Time	加工時間	8.5min / 8.5分



Point of Requirement 需求重點

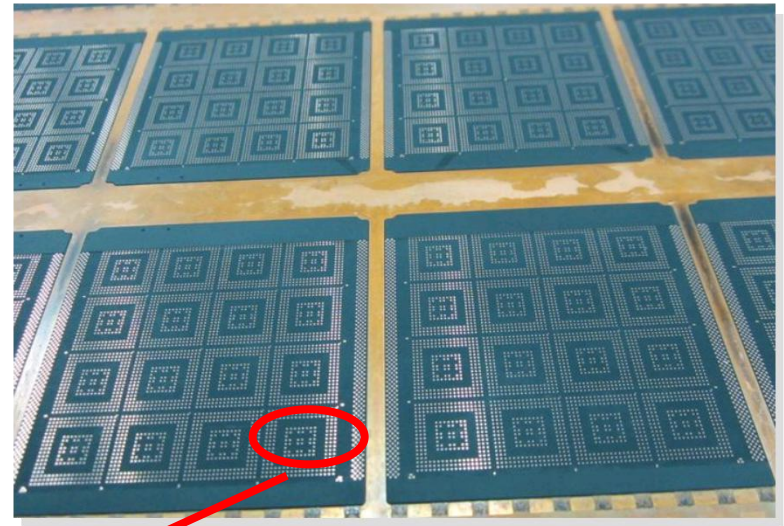
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It takes you only 10 mins to manage to use auto probe and compensation by smart grinders with high efficiency and total solution.

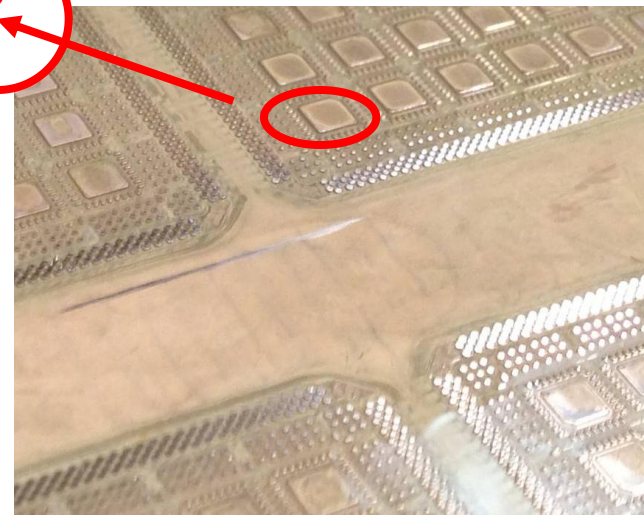
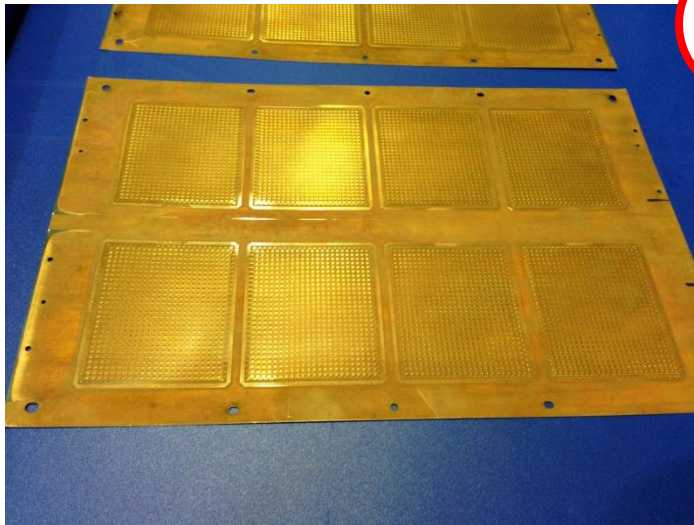
SMART 自動量測與補正之速成與高效能與完整解決方案

Point of Requirement / 需求重點	Specifications or Accuracy / 規格或精度
Grinding Wheel / 砂輪型式	GC-320-H-10-V (Brand:Kinik Taiwan)
Demension Accuracy / 尺寸精度	±0.008mm
Surface Roughness / 工件粗度	Ra 0.2 μ m

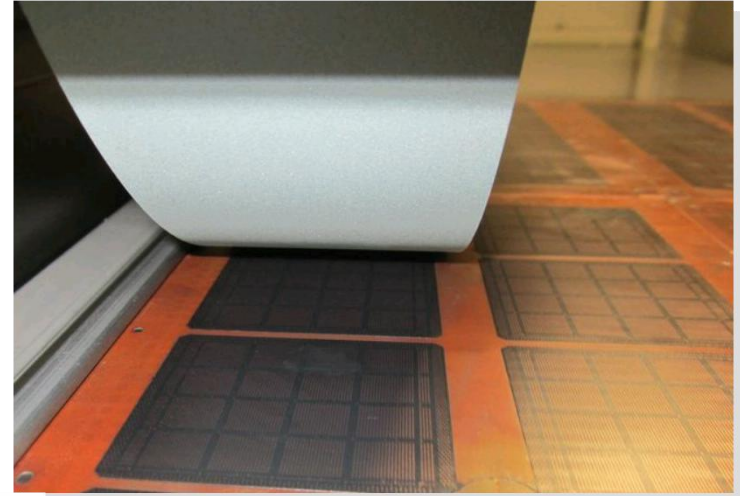
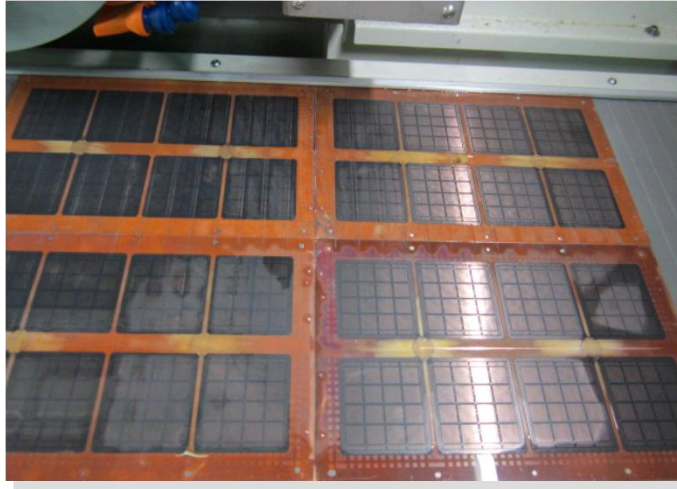
10. Chip of IC / IC晶片



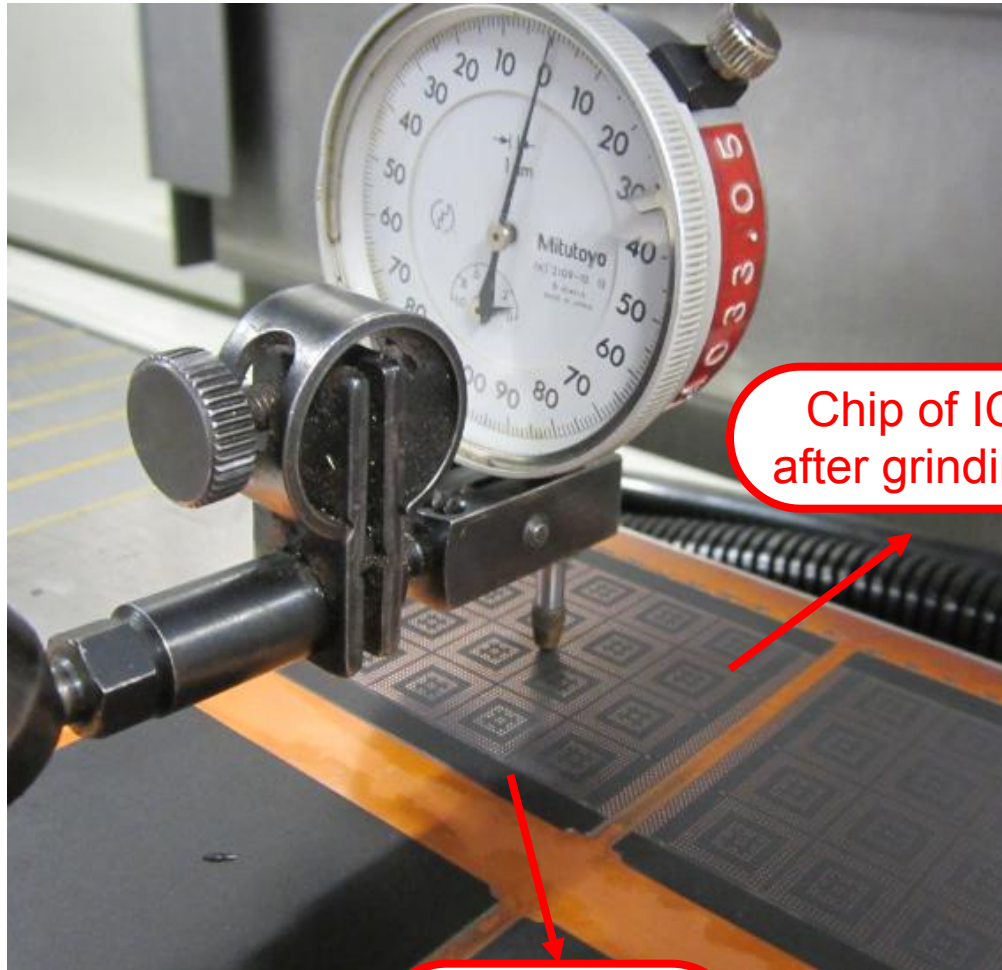
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10. Chip of IC / IC晶片

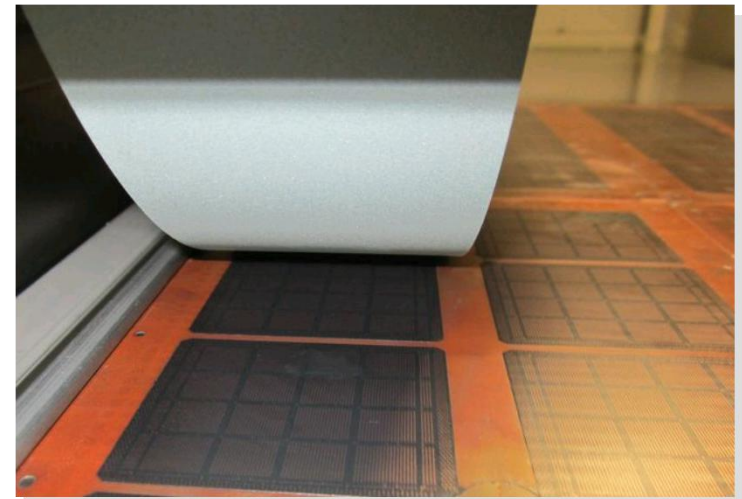
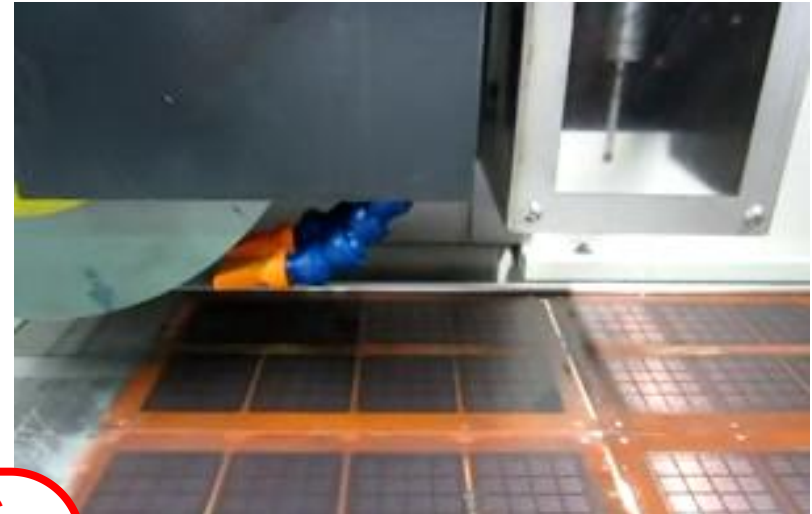


10. Chip of IC / IC晶片



Chip of IC
after grinding

Chip of IC
Before grinding



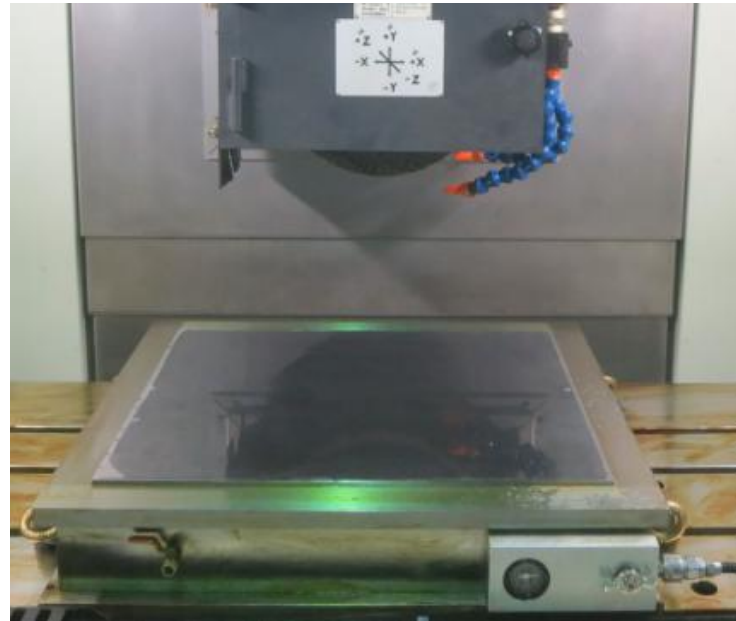
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材料：
環氧樹脂 (Epoxy)

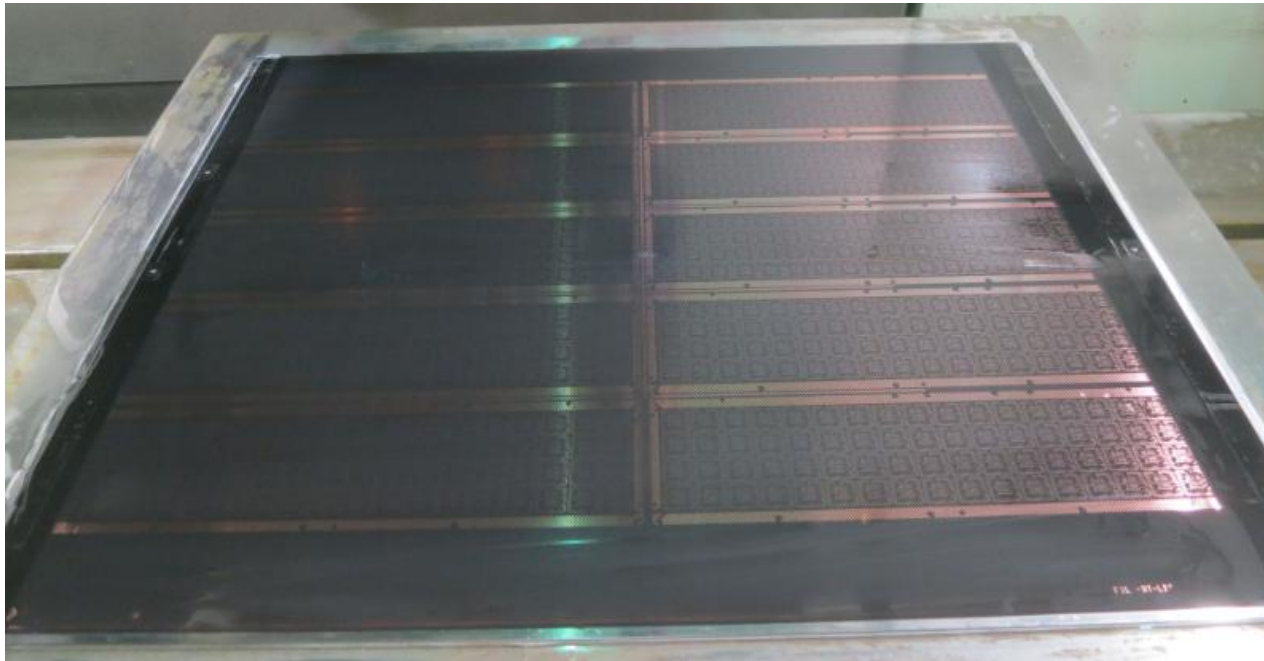
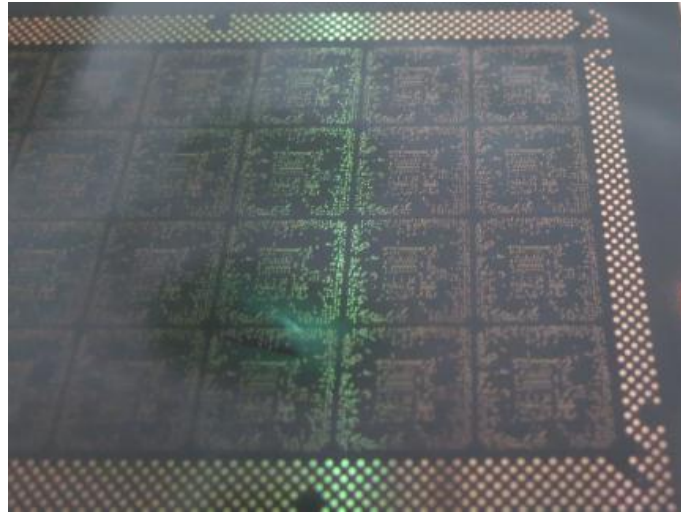
材料隨著半導體構裝的功能複雜性與小型化、高密度的提升，且顧及到低功率損失等特性，載板的線寬/線距亦隨之朝細線化演進。再從載板結構的製程比較：隨著半導體模組封裝的元件內容越來越多，從單一 IC 的疊構，到多種 IC 的堆疊，從垂直導通的連結，深化到內埋元件的載板 (Embedded Substrate)，系統封裝 (System in Package 簡稱 SiP) 用模組載板所內埋的已經不只單一被動元件。

對於半導體整體構裝而言，薄化能力是電子產品組裝追求的方向，半導體構裝材料的可靠性隨著 IC 要導入車用電子、穿戴式裝置、或是置於極端環境下的物聯網 (IoT) 產品時，尤其對載板的可靠性要求也會隨之提高，散熱性是最近下游構裝廠強調的趨勢與需求。

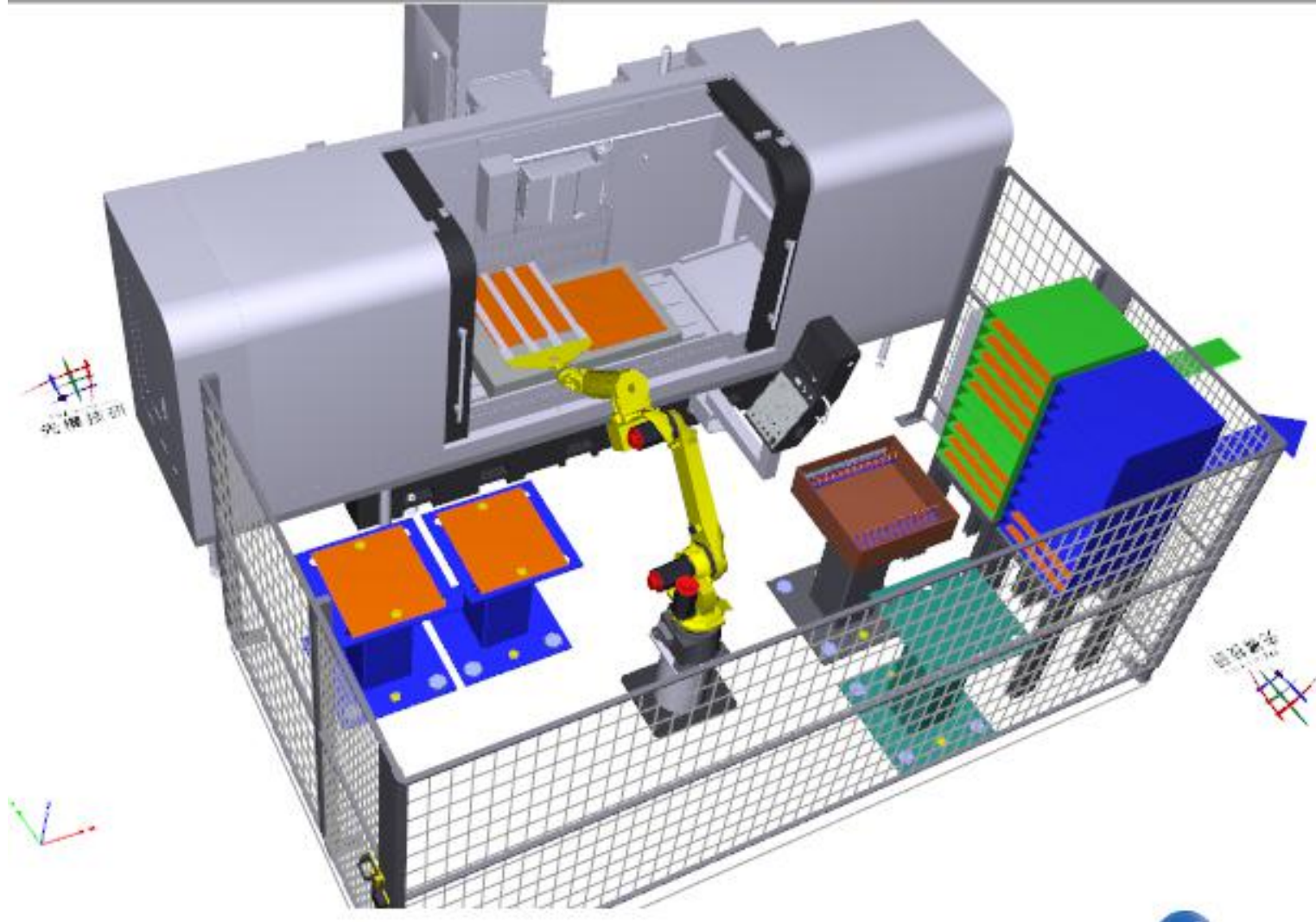
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